

PRELIMINARY SPEC

Part Number: AA5060SEC/J

HYPER ORANGE

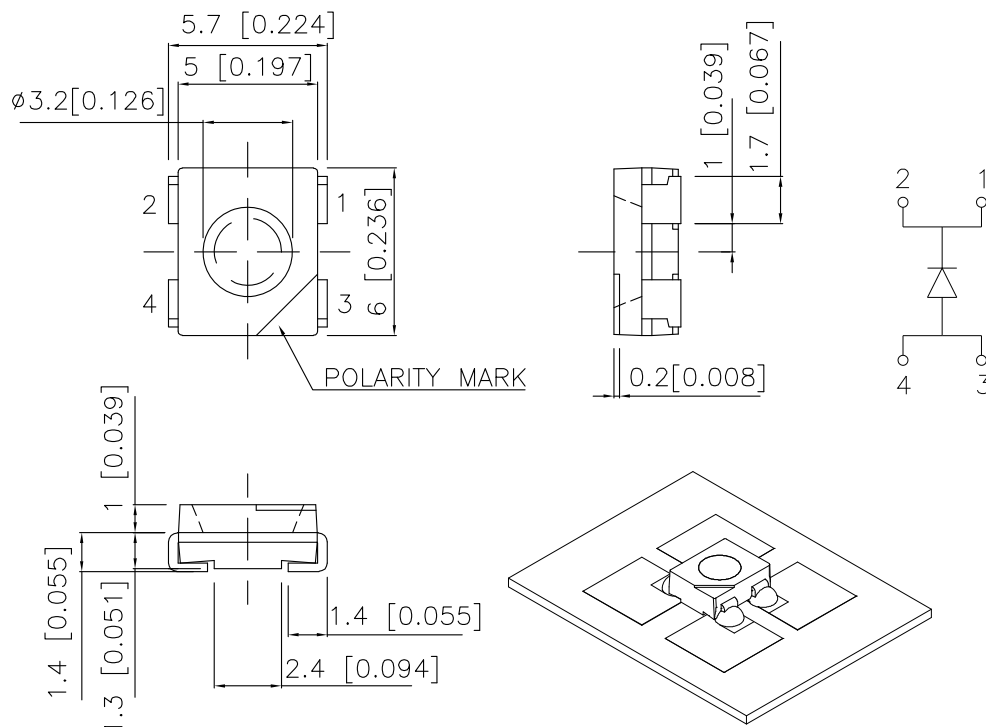
Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE : 500PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.

Description

The Super Bright device is based on light emitting diode chip made from AlInGaP.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2 θ 1/2
AA5060SEC/J	HYPERS ORANGE (AlInGaP)	WATER CLEAR	3300	4500	100°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

2. Luminous Intensity / Luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Hyper Orange	640		nm	IF=20mA
λ_D [1]	Dominant Wavelength	Hyper Orange	630		nm	IF=20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Hyper Orange	25		nm	IF=20mA
C	Capacitance	Hyper Orange	27		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Orange	2.2	2.8	V	IF=20mA
IR	Reverse Current	Hyper Orange		10	uA	VR = 5V

Notes:

1. Wavelength: +/-1nm.

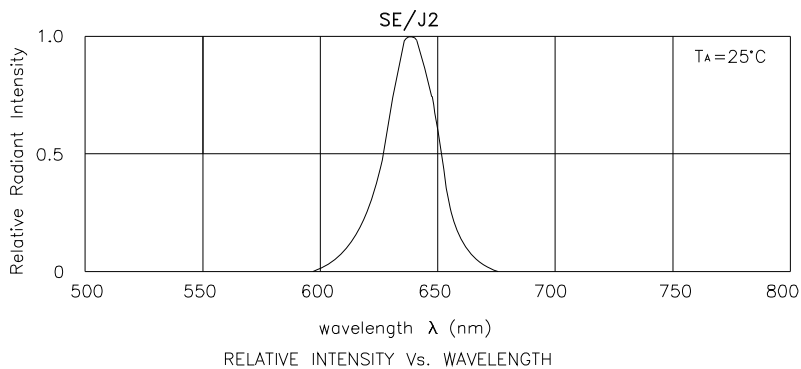
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Orange	Units
Power dissipation	140	mW
DC Forward Current	50	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

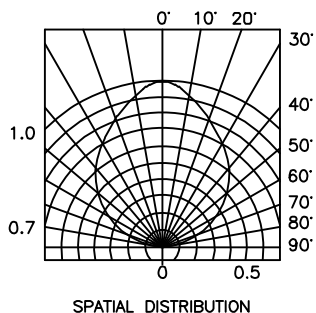
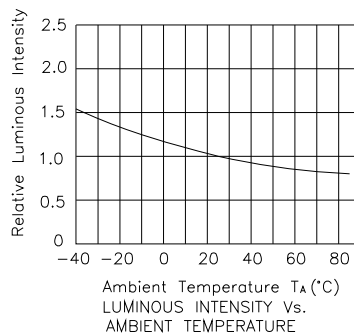
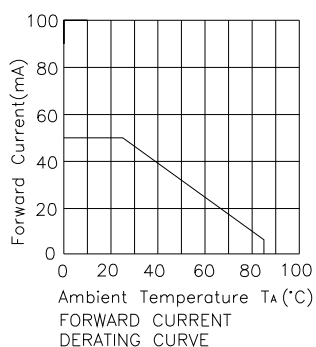
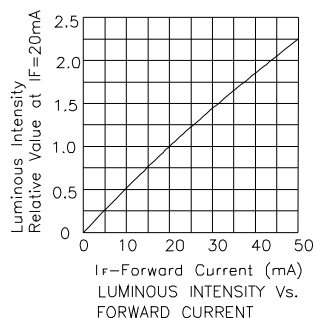
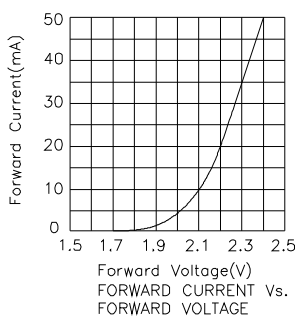
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



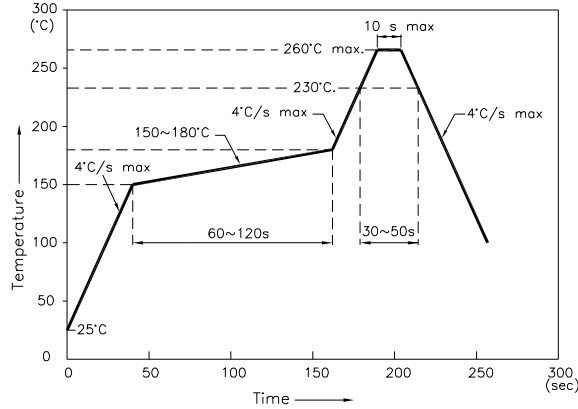
Hyper Orange

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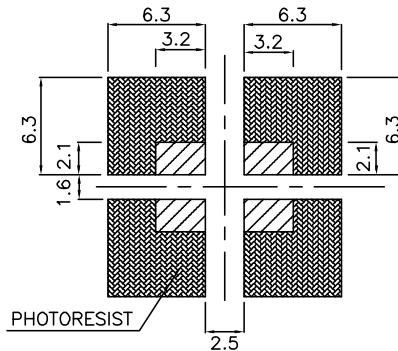
Reflow Soldering Profile For Lead-free SMT Process.



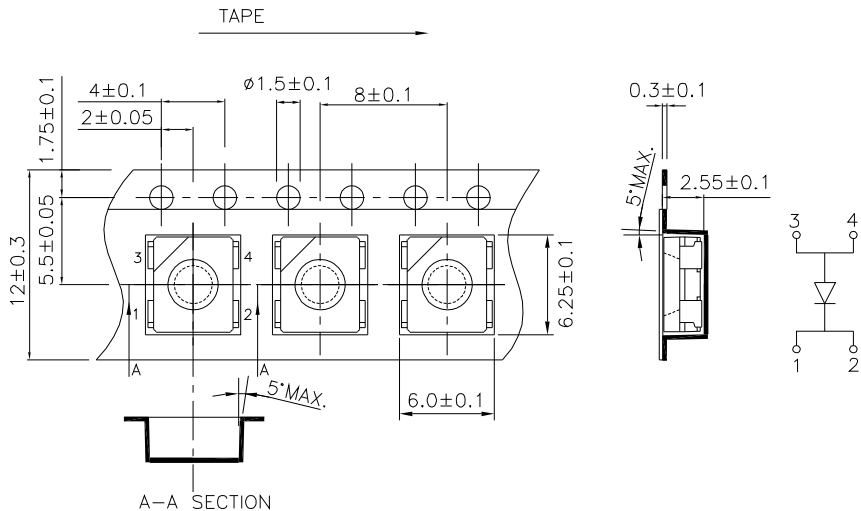
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm; Tolerance: ±0.1)

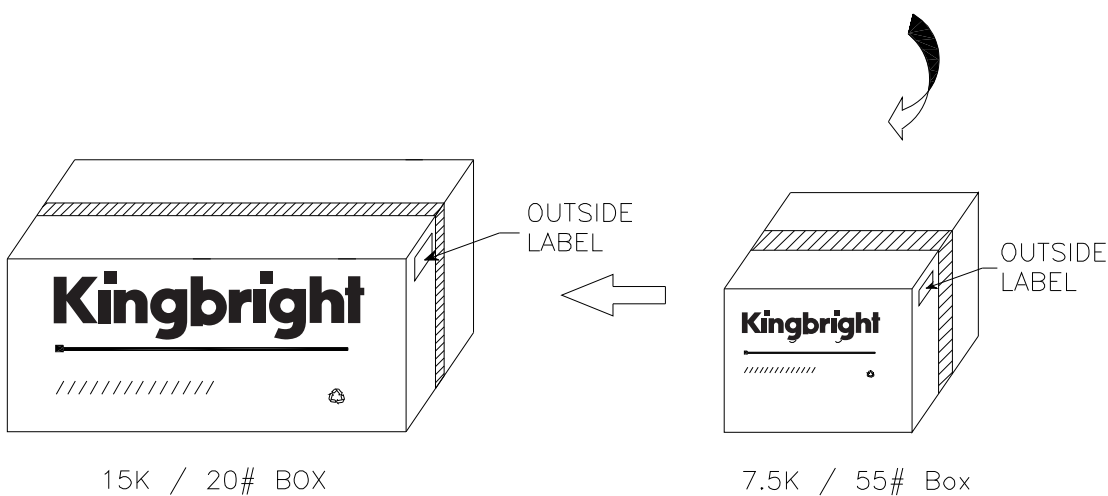
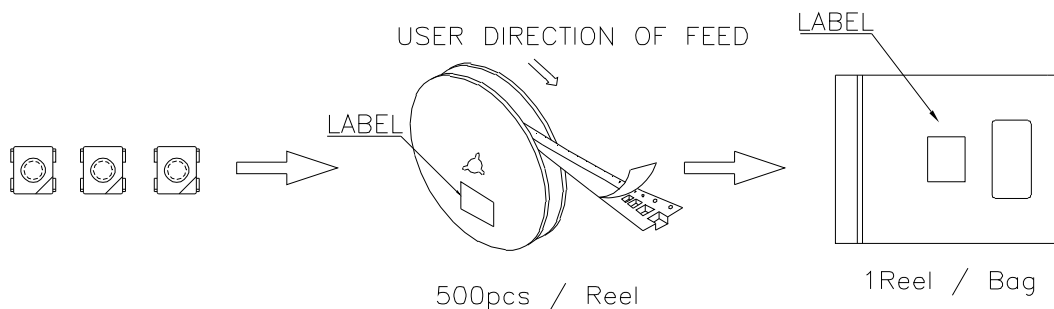



Tape Specifications (Units : mm)



PACKING & LABEL SPECIFICATIONS

AA5060SEC/J



<h1>Kingbright</h1>	
P/NO: AA5060xxx	
QTY: 500 pcs	Q.C. Q C xx-xx-xxxx PASSED
S/N: XXXX	
CODE: XXX	
LOT NO:	
 <small>xxxxxxxxxxxxxxxxxxxxxxxxxxxxxxxx</small>	
RoHS Compliant	